Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 96138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A0905-01R1

DATE: July 30, 2009

Product Affected: 7 mm x 7 mm x 1.4 mm TQFP-48 (Green)

Date Effective: August 15, 2009

MEANS OF DISTINGUISHING CHANGED DEVICES:

☐ Product Mark
☐ Back Mark
☐ Date Code
☒ Other Change in Product Part Number (Refer Attachment 2)

Contact: Mary Vesey
Title: Director, Product Assurance
Phone #: (408) 284-4565
Fax #: (408) 284-1450
E-mail: Mary.Vesey@.com

Attachment: ☒ Yes ☐ No

Samples: Contact your local samples representative for sample requests.

DESCRIPTION AND PURPOSE OF CHANGE:

☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☐ Material
☐ Testing
☐ Manufacturing Site
☐ Data Sheet
☒ Other - Package Obsolete

Revision 1: This revised notification is to correct the replacement part# from 843S06EYLF / 843S06EYLFT to 843S06FYLF / 843S06FYLFT.

PCN effective date remain unchanged.

Refer to attachment for a copy of the original PCN, PCN# A0905-01.

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________

DATE: ____________________

Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 96138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A0905-01 DATE: May 15, 2009

Product Affected: 7 mm x 7 mm x 1.4 mm TQFP-48 (Green)

Date Effective: August 15, 2009

MEANS OF DISTINGUISHING CHANGED DEVICES:
- ☐ Product Mark
- ☐ Back Mark
- ☐ Date Code
- ■ Other Change in Product Part Number (Refer Attachment 2)

Contact: Mary Vesey
Title: Director, Product Assurance
Phone #: (408) 284-4565
Fax #: (408) 284-1450
E-mail: Mary.Vesey@.com

Attachment: ■ Yes ☐ No

Samples: Contact your local samples representative for sample requests.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ■ Other - Package Obsolete

This notification is to advise our customers that IDT is obsoleting the 1.4 mm thick TQFP-48 (7 mm x 7 mm x 1.4 mm) package. This package will be replaced by 1.0 mm thick TQFP-48 (7 mm x 7 mm x 1.0 mm) package.

Attachment 1 outlines the qualification plan and results.
Attachment 2 shows the affected part numbers and replacement part numbers.
Attachment 3 shows the new POD and datasheet.

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 96138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 1 - PCN # : A0905-01

PCN Type: Package Obsolete

Data Sheet Change: Yes

Detail Of Change:

This notification is to advise our customers that IDT is obsoleting the 1.4 mm thick TQFP-48 (7 mm x 7 mm x 1.4 mm) package. This package will be replaced by 1.0 mm thick TQFP-48 (7 mm x 7 mm x 1.0 mm) package.

Refer to Table 1 for assembly material sets used and qualified assembly locations for the new package.

There is no change to the moisture performance or RoHS compliance.

There is no change required to the board land pattern layout as a result of this change.

During the transition period, IDT will continue to support customer shipments with inventory build at the existing assembly locations. IDT does not anticipate any impact on the product availability.

We request you to acknowledge receipt of this notification within 30 days of the date of this PCN notification. If you require samples to conduct evaluations, please make your sample request within 30 days as samples are not built ahead of the change. You may contact your local sales representative to acknowledge this PCN and request samples.

Table 1

Description	Old	New
Package Dimensions (Width x Length x Thickness)	7 mm x 7 mm x 1.4 mm	7 mm x 7 mm x 1.0 mm
Internal Package Nomenclature	ESG48	DXG48
Assembly Location	ASAC, China	Amkor, Korea
Assembly Materials	Die Attach: 2200	Ablestik 3230
	Wire: Au wire	Au wire
	Mold Compound: G700 series	G700 series
	Lead Frame: Copper Alloy	Lead Frame: Copper Alloy
	Plating: Matte 100% Sn (Green)	Plating: Matte 100% Sn (Green)

ATTACHMENT 1 - PCN # : A0905-01

Qualification Information and Qualification Data:

Qualification Test Plans and Results:

Qual Vehicle: 7 mm x 7 mm x 1 mm TQFP-48 (3 lots)

Test Description	Test Method	Test Results (SS / Rej)
* High Accelerated Stress Test (130 °C/85% RH, 96 Hrs)	JESD22-A118	45/0, 45/0, 45/0
* Temperature Cycle (-65 °C to +150 °C, 500 Cyc)	JESD22-A104	76/0, 76/0, 76/0

Note: * Test require moisture pre-conditioning sequence per JEDEC J-STD-020

ATTACHMENT 2 - PCN #: A0905-01

Affected Part Number

Obsolete Part Number	Replacement Part Number
843S06BYLF	843S06EYLF
843S06BYLFT	843S06EYLFT